



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



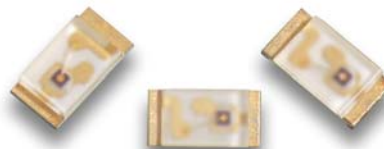
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APG1608ZGCK

1.6 x 0.8 x 0.25 mm (0603) SMD Chip LED Lamp

DESCRIPTIONS

- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode
- Electrostatic discharge and power surge could damage the LEDs
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- All devices, equipments and machineries must be electrically grounded

FEATURES

- 1.6 mm x 0.8 mm SMD LED, 0.25 mm thickness
- Low power consumption
- Wide viewing angle
- Compatible with automatic placement equipment
- Ideal for backlight and indicator
- Package: 4000 pcs / reel
- Moisture sensitivity level: 3
- RoHS compliant

APPLICATIONS

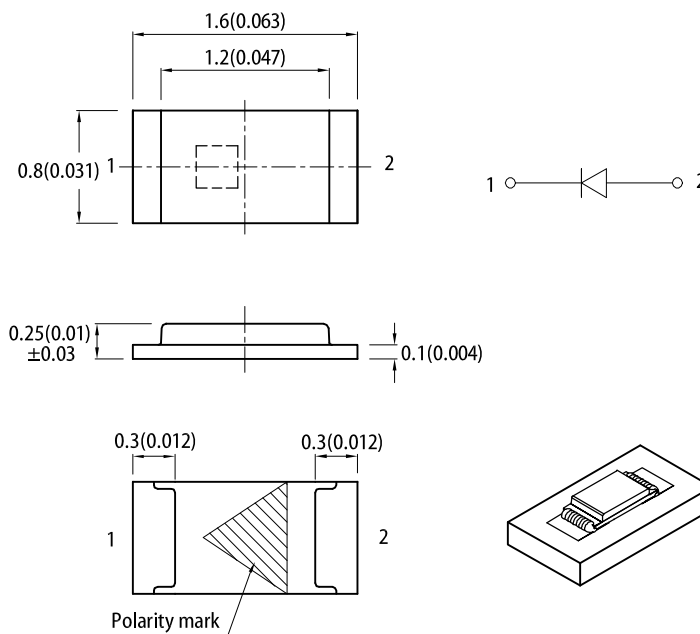
- Backlight
- Status indicator
- Home and smart appliances
- Wearable and portable devices
- Healthcare applications

ATTENTION

Observe precautions for handling electrostatic discharge sensitive devices

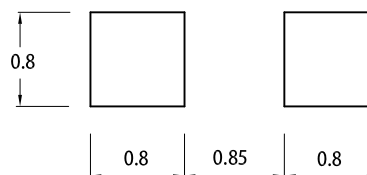


PACKAGE DIMENSIONS



RECOMMENDED SOLDERING PATTERN

(units : mm; tolerance : ± 0.1)



Mask open area ratio: 80%
Mask thickness: 80~100um

Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.1(0.004") unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.

SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	Iv (mcd) @ 20mA ^[2]		Viewing Angle ^[1]
			Min.	Typ.	2θ1/2
APG1608ZGCK	■ Green (InGaN)	Water Clear	300	400	130°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity / luminous flux: +/-15%.
3. Luminous intensity value is traceable to CIE127-2007 standards.

ELECTRICAL / OPTICAL CHARACTERISTICS at $T_A=25^{\circ}\text{C}$

Parameter	Symbol	Emitting Color	Value		Unit
			Typ.	Max.	
Wavelength at Peak Emission $I_F = 20\text{mA}$	λ_{peak}	Green	515	-	nm
Dominant Wavelength $I_F = 20\text{mA}$	$\lambda_{\text{dom}}^{[1]}$	Green	525	-	nm
Spectral Bandwidth at 50% Φ REL MAX $I_F = 20\text{mA}$	$\Delta\lambda$	Green	35	-	nm
Capacitance	C	Green	45	-	pF
Forward Voltage $I_F = 20\text{mA}$	$V_F^{[2]}$	Green	3.3	4.1	V
Reverse Current ($V_R = 5\text{V}$)	I_R	Green	-	50	μA
Temperature Coefficient of λ_{peak} $I_F = 20\text{mA}$, $-10^{\circ}\text{C} \leq T \leq 85^{\circ}\text{C}$	$\text{TC}_{\lambda_{\text{peak}}}$	Green	0.05	-	$\text{nm}/^{\circ}\text{C}$
Temperature Coefficient of λ_{dom} $I_F = 20\text{mA}$, $-10^{\circ}\text{C} \leq T \leq 85^{\circ}\text{C}$	$\text{TC}_{\lambda_{\text{dom}}}$	Green	0.03	-	$\text{nm}/^{\circ}\text{C}$
Temperature Coefficient of V_F $I_F = 20\text{mA}$, $-10^{\circ}\text{C} \leq T \leq 85^{\circ}\text{C}$	TC_V	Green	-3.0	-	$\text{mV}/^{\circ}\text{C}$

Notes:

- The dominant wavelength (λ_d) above is the setup value of the sorting machine. (Tolerance $\lambda_d : \pm 1\text{nm}$.)
- Forward voltage: $\pm 0.1\text{V}$.
- Wavelength value is traceable to CIE127-2007 standards.
- Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

ABSOLUTE MAXIMUM RATINGS at $T_A=25^{\circ}\text{C}$

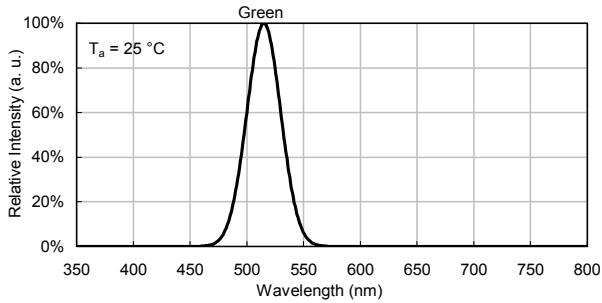
Parameter	Symbol	Value	Unit
Power Dissipation	P_D	102.5	mW
Reverse Voltage	V_R	5	V
Junction Temperature	T_j	115	$^{\circ}\text{C}$
Operating Temperature	T_{op}	-40 to +85	$^{\circ}\text{C}$
Storage Temperature	T_{stg}	-40 to +85	$^{\circ}\text{C}$
DC Forward Current	I_F	25	mA
Peak Forward Current	$I_{\text{FM}}^{[1]}$	150	mA
Electrostatic Discharge Threshold (HBM)	-	450	V
Thermal Resistance (Junction / Ambient)	$R_{\text{th JA}}^{[2]}$	570	$^{\circ}\text{C}/\text{W}$
Thermal Resistance (Junction / Solder point)	$R_{\text{th JS}}^{[2]}$	420	$^{\circ}\text{C}/\text{W}$

Notes:

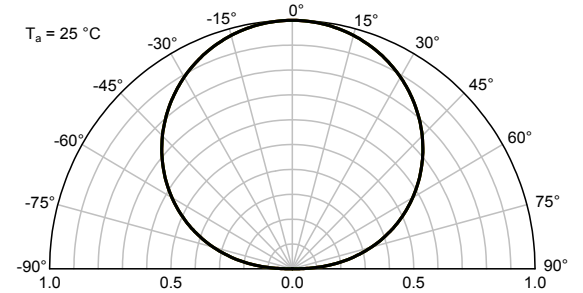
- 1/10 Duty Cycle, 0.1ms Pulse Width.
- $R_{\text{th JA}}, R_{\text{th JS}}$ Results from mounting on PC board FR4 (pad size $\geq 16\text{mm}^2$ per pad).
- Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

TECHNICAL DATA

RELATIVE INTENSITY vs. WAVELENGTH

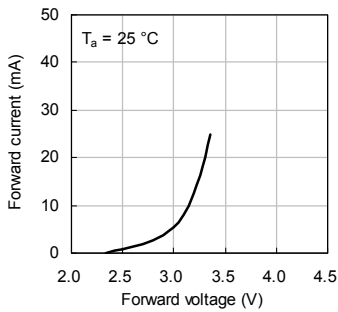


SPATIAL DISTRIBUTION

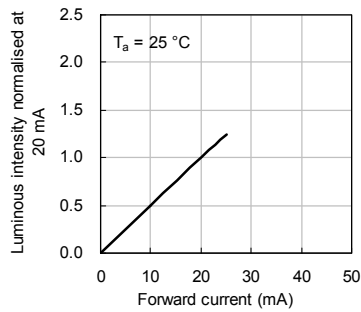


GREEN

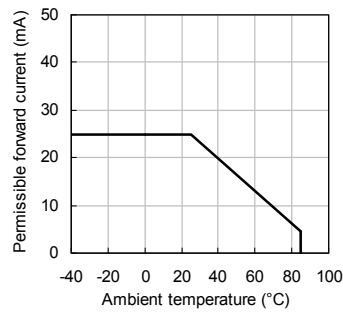
Forward Current vs. Forward Voltage



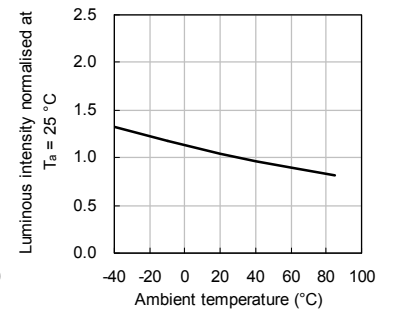
Luminous Intensity vs. Forward Current



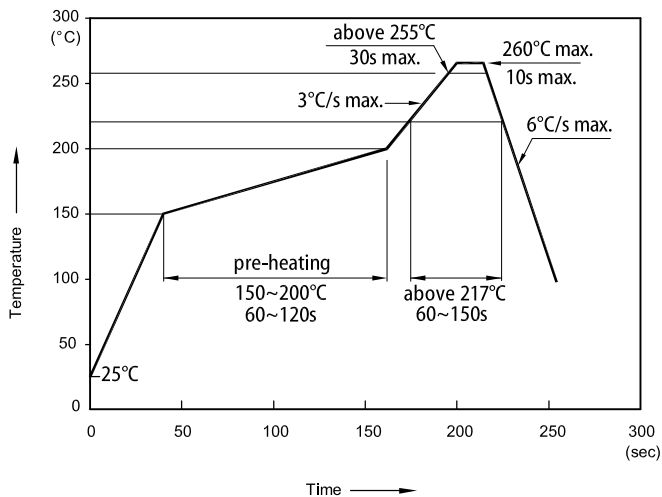
Forward Current Derating Curve



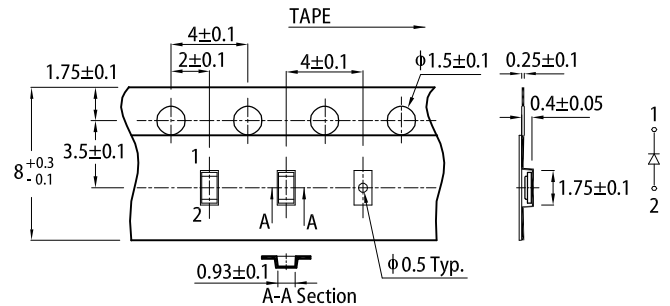
Luminous Intensity vs. Ambient Temperature



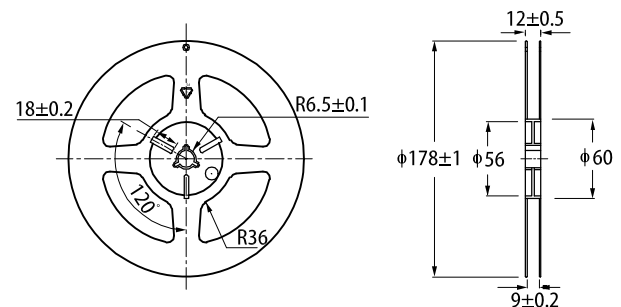
REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS



TAPE SPECIFICATIONS (units : mm)

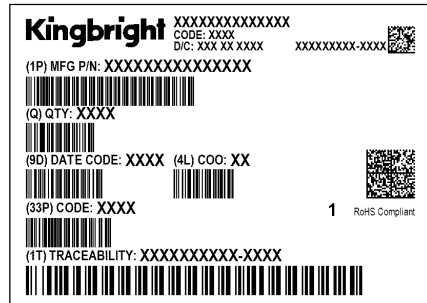
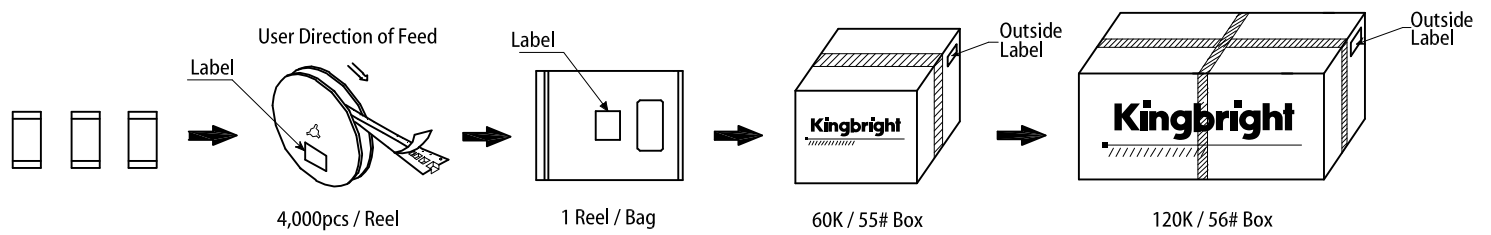


REEL DIMENSION (units : mm)



- Notes:
1. Don't cause stress to the LEDs while it is exposed to high temperature.
 2. The maximum number of reflow soldering passes is 2 times.
 3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

PACKING & LABEL SPECIFICATIONS



PRECAUTIONARY NOTES

1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.
2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
3. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
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